

(0.80 mm) .0315"

MEC8-RA, MEC8-EM SERIES

# RIGHT-ANGLE/EDGE MOUNT SOCKETS

**Mates with:**

(1.60 mm) .062" thick card

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC8-RA](http://www.samtec.com?MEC8-RA)

**Insulator Material:** Black LCP

**Contact Material:** Phosphor Bronze

**Plating:**

Au or Sn over 50 μm (1.27 μm) Ni

**Operating Temp Range:**

-55 °C to +125 °C

**Insertion Depth:**

(3.94 mm) .155" to

(6.25 mm) .246"

**Current Rating:**

2.0 A per pin

(6 adjacent pins powered)

**Voltage Rating:** 265 VAC

**RoHS Compliant:** Yes

**Lead-Free Solderable:** Yes

**RECOGNITIONS**

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



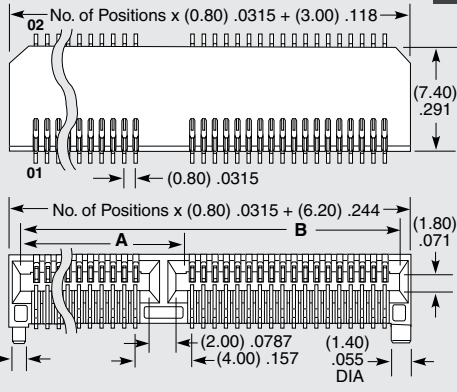
**MEC8** - **1** POSITIONS PER ROW - **02** PLATING OPTION - **D** - **RA1** - OTHER OPTION

**10, 13, 20, 25, 30, 37, 40, 49, 50**

**-L**  
= 10 μm (0.25 μm) Gold on contact, Matte Tin on tail

**-TR**  
= Tape & Reel Packaging

POS. PER ROW	A	B
13	(6.10) .240	(15.00) .591
25	(18.10) .713	(34.20) 1.346
37	(18.90) .744	(36.60) 1.441
40	(22.90) .902	(43.80) 1.724
49	(22.90) .902	(44.60) 1.756
50		



**HIGH-SPEED CHANNEL PERFORMANCE**

**MEC8-RA**

Rating based on Samtec reference channel. For full SI performance data visit [Samtec.com](http://Samtec.com) or contact SIG@samtec.com

**18**  
Gbps

**ALSO AVAILABLE (MOQ Required)**

- 1 mm mating card thickness option
- Latching option
- Elevated Contact Samtec.

**Mates with:**

(1.60 mm) .062" thick card

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC8-EM](http://www.samtec.com?MEC8-EM)

**Insulator Material:** Black LCP

**Contact Material:** Phosphor Bronze

**Plating:**

Au or Sn over 50 μm (1.27 μm) Ni

**Operating Temp Range:**

-55 °C to +125 °C

**Insertion Depth:**

(4.32 mm) .170" to

(5.66 mm) .223"

**Current Rating:**

1.8 A per pin

(6 adjacent pins powered)

**Voltage Rating:** 265 VAC

**RoHS Compliant:** Yes

**Lead-Free Solderable:** Yes

**RECOGNITIONS**

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)

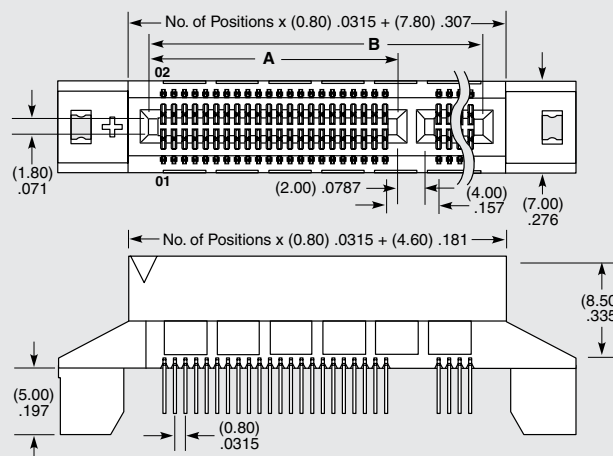


**MEC8** - **1** POSITIONS PER ROW - **02** PLATING OPTION - **D** - **EM2**

**10, 20, 30, 40, 50, 60, 70**

**-L**  
= 10 μm (0.25 μm) Gold on contact, Matte Tin on tail

**EM2**  
= (1.60 mm) .062" thick PCB



**HIGH-SPEED CHANNEL PERFORMANCE**

**MEC8-EM**

Rating based on Samtec reference channel. For full SI performance data visit [Samtec.com](http://Samtec.com) or contact SIG@samtec.com

**19**  
Gbps

POSITIONS PER ROW	A	B
40	(18.90) .744	(36.60) 1.441
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071
70	(30.90) 1.217	(60.60) 2.386

**ALSO AVAILABLE (MOQ Required)**

- 1 mm mating card thickness option
- Contact Samtec.